

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XP161A1355PR-G

Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.272	Silicon	24000	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	24.392	Copper	460200	7440-50-8
		Tin	300	7440-31-5
		Silver	4100	7440-22-4
Die attach	0.115	Silver	2200	7440-22-4
		Epoxy	600	—
		Inorganic compound	200	—
		Antimony trioxide	100	1309-64-4
Bonding wire	0.236	Gold	4500	7440-57-5
Resin	21.312	Silica	402100	60676-86-0
		Epoxy resin	36400	—
		Phenol resin	30200	—
		Metal hydroxide	27600	—
Plating	0.400	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."